

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number PMEG40T50EP-Q Part Description											
									Nexperia DHAM	Schottky			
									SMD package				
		Test Conditions	Duration	# Lots	# Quantity	# Rejects							
			TEST										
			Pre- and Post-Stress										
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below							
		JESD22-A113											
		Bake Tamb = 125 °C	24 hours										
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours										
# A1	Preconditioning	Reflow soldering	3 cycles	1514	64430	0							
		MIL-STD-750-1											
	HTRB	M1038 Method A											
		Tj = Tjmax, Vr = 100% of max. datasheet											
# B1	Bias	reverse voltage ^[1]	1000 hours	206	9320	0							
		JECD22 4404											
	TC	JESD22-A104	1000	244	1 1000								
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0							
	UHAST	JESD22-A118											
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %											
# A3 alt	Olibiasea lines l	IESD22-A102	- 96 hours	311	14080	0							
	AC	Tamb = 121 °C, RH = 100 %											
	Autoclave	Pressure = 205 kPa (29.7 psia)											
# A3 dit	, lacocia re	Tressure Los III a (Estr pola)											
	H3TRB	JESD22-A101											
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of											
# A2 alt	Temperature Reverse Bias	rated reverse voltage ^{[1], [2]}	1000 hours	311	14080	0							
" ALL GIC		MIL-STD-750 Method 1037				-							
	IOL	ton = toff, devices powered to insure ΔT_j =											
# A5	Intermittent Operating Life		1000 hours	312	14120	0							
	· · · ·												
	RSH	JESD22-A111											
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	269	8070	0							
	SD												
# C10	Solderability	J-STD-002		222	6660	0							

^[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)
Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

© 2024 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com

 $^{\[2\]}$ The maximum applied voltage is limited by test chamber set up and does not exceed 115V.